

Specification Sheet

CIGT201610LH1R0MNE (2016 / EIA 0806)



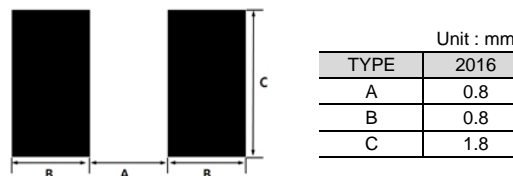
APPLICATION

Smart phones, Tablet, Wearable devices, Power converter modules, etc.

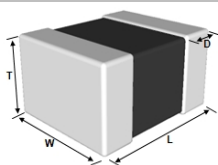
FEATURES

- Small power inductor for mobile devices
- Low DCR structure and high efficiency inductor for power circuits.
- Monolithic structure for high reliability
- Free of all RoHS-regulated substances
- Halogen free

RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
2016	2.0±0.2	1.6±0.2	1.0 max	0.5±0.2

DESCRIPTION

Part no.	Size [inch/mm]	Thickness [mm] (max)	Inductance [uH]	Inductance tolerance (%)	DC Resistance [mΩ]		Rated DC Current (Isat) [A]		Rated DC Current (Irms) [A]	
					Max.	Typ.	Max.	Typ.	Max.	Typ.
CIGT201610LH1R0MNE	0806/2016	1.0	1.0	±20	57	50	3.6	3.9	2.8	3.1

- * Inductance : Measured with a LCR meter 4991A(Agilent) or equivalent (Test Freq. 1MHz, Level 0.1V)
- * DC Resistance : Measured with a Resistance HI-TESTER 3541(HIOKI) or equivalent
- * Maximum allowable DC current : Value defined when DC current flows and the initial value of inductance has decreased by 30% or when current flows and temperature has risen to 40 °C whichever is smaller. (Reference: ambient temperature is 25 °C ±10)
- (Isat) : Allowable current in DC saturation : The DC saturation allowable current value is specified when the decrease of the initial inductance value at 30% (Reference: ambient temperature is 25 °C ±10)
- (Irms) : Allowable current of temperature rise : The temperature rise allowable current value is specified when temperature of the inductor is raised 40 °C by DC current. (Reference: ambient temperature is 25 °C ±10)
- * Absolute maximum voltage : Absolute maximum voltage DC 20V.
- * Operating temperature range : -40 to +125°C (Including self-temperature rise)

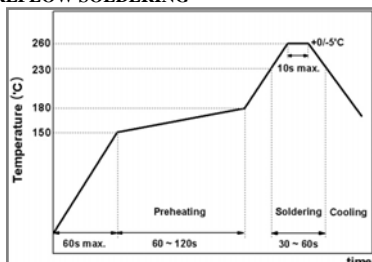
PRODUCT IDENTIFICATION

CIG T 2016 10 LH 1R0 M N E
(1) (2) (3) (4) (5) (6) (7) (8) (9)

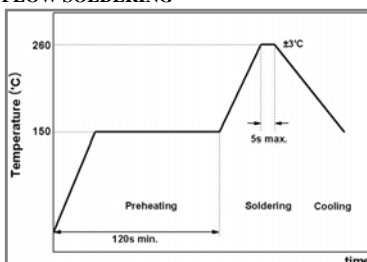
- (1) Power Inductor
- (2) Type (T: Metal Composite Thin Film Type)
- (3) Dimension (2016: 2.0mm x1.6 mm)
- (4) Thicknes (10: 1.0mm)
- (5) Remark (Characterization Code)
- (6) Inductan (1R0: 1.0 uH)
- (7) Toleranc (M:±20%)
- (8) Internal Code
- (9) Packaging (C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



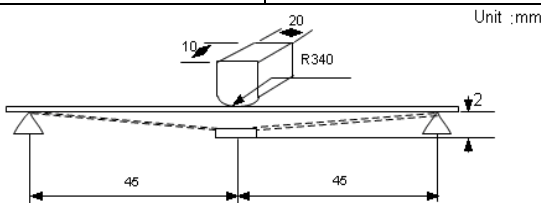
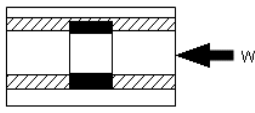
IRON SOLDERING

Temperature of Soldering Iron Tip	280 °C max.
Preheating Temperature	150 °C min.
Temperature Differential	ΔT ≤ 130 °C
Soldering Time	3sec max.
Wattage	50W max.

PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3000 pcs

Reliability Test

Item	Specified Value	Test Condition	
Solderability	More than 90% of terminal electrode should be soldered newly.	After being dipped in flux for 4±1 seconds, and preheated at 150~180℃ for 2~3 min, the specimen shall be immersed in solder at 245±5℃ for 4±1 seconds.	
Resistance to Soldering	No mechanical damage. Remaining terminal Electrode: 75% min. Inductance change to be within ±20% to the initial.	After being dipped in flux for 4±1 seconds, and preheated at 150~180℃ for 2~3 min, the specimen shall be immersed in solder at 260±5℃ for 10 ±0.5 seconds.	
Thermal Shock (Temperature Cycle test)	No mechanical damage Inductance change to be within ±20% to the initial.	Repeat 100 cycles under the following conditions. -40±3℃ for 30 min → 85±3℃ for 30 min	
High Temp. Humidity Resistance Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, 85%RH, for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.	
Low Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at -55±2℃ for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24hours.	
High Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at 125±2℃ for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24hours.	
High Temp. Humidity Resistance Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, 85%RH, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.	
High Temperature Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.	
Reflow Test	No mechanical damage Inductance change to be within ±20% to the initial	Peak 260±5℃, 3 times	
Vibration Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Vibrate as apply 10~55Hz, 1.5mm amplitude for 2 hours in each of three(X,Y,Z) axis (total 6 hours).	
Bending Test	No mechanical damage	Bending Limit; 2mm Test Speed; 1.0mm/sec. Keep the test board at the limit point in 5 sec. PCB thickness : 1.6mm	
			
Terminal Adhesion Test	No indication of peeling shall occur on the terminal electrode.	W(kgf)	TIME(sec)
			0.5
Drop Test	No mechanical damage Inductance change to be within ±20% to the initial.	Random Free Fall test on concrete plate. 1 meter, 10 drops	
Ipeak (AC+DC Load Life)	No mechanical damage Inductance change to be within ±20% to the initial	85±2℃, 85%RH, Load(Ipeak) for 120 hours. (Frequency:1MHz, Load(Ipeak):1.5hr on / 0.5hr off) Measure the test items after leaving at normal temperature and humidity for 24 hours. * Load(Ipeak) = Irms(max)×1.4	